

ICOPEN 2018

INTERNATIONAL CONFERENCE ON
OPTICAL AND PHOTONIC ENGINEERING

08 - 11 MAY 2018 • SHANGHAI, CHINA

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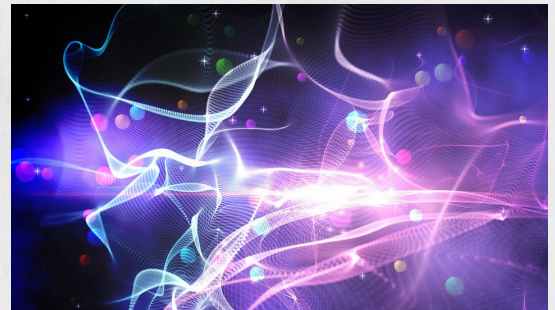
ABOUT ICPEN 2018

Following the success of icOPEN 2016 in Chengdu, OPSS is proud to continue **icOPEN 2018** in Shanghai, China.

Organised and hosted by OPSS, and co-organized by Shanghai University, Chinese Laser Press and OPSS China Chapter, this event will be held in **Shanghai, China** during **May 08-11, 2018**. icOPEN2018 will provide a timely platform to conduct a recap of the latest technologies and industry milestones, and promote optical and photonic engineering to a wider audience.

CONFERENCE HIGHLIGHTS

- **Prof. Anand Asundi**, Centre for Optical and Laser Engineering, Nanyang Technological University, Singapore will be the Conference General Chair. **Prof. Yu Yingjie**, Shanghai University, China; **Prof. Zuo Chao**, Nanjing University of Science and Technology, China and **Prof. Qian Kemao**, Nanyang Technological University, Singapore will be the Conference Co-chairs.
- All accepted papers will be published by **SPIE Conference Proceedings**, which will be included in **SPIE Digital Library**, provided to the Web of Science Conference Proceedings Citation Index-Science, **Scopus**, **Ei Compendex**, and others, to ensure maximum awareness of the Proceedings.
- **ORBEC 3-D Sensor Application Design Competition** and **GratingMaster Cup Optical Engineering Design Competition** will be host for students, researchers and engineers to participate.



CALL FOR PAPERS

Conference topics of interest include but not limited to the following :

- **High Resolution Optical Metrology**
- **Digital Holography and Quantitative Phase Imaging**
- **3D Computer Vision**
- **Image Processing and Deep Learning**
- **3D Image Acquisition and Display**
- **Non-Destructive Testing and Inspection**
- **Photomechanics**
- **Laser micro-nano processing and Patterning**
- **Diffraction and Freeform Fabrication and Testing**
- **Optical component and system simulation**
- **Optical functional materials and devices**
- **Fiber Optics and sensing technology**
- **Biomedical Optics and Imaging**
- **Ultrafast Lasers and Applications**

IMPORTANT DATES

- **Abstract Submission Deadline** February 05, 2018
- **Notification Day** March 15, 2018
- **Full Paper Submission Deadline** April 01, 2018
- **Early Bird Registration Deadline Day** April 01, 2018
- **Registration Deadline** April 15, 2018
- **Final Paper Submission Deadline** April 30, 2018

CONTACT

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For more information about icOPEN 2018 please visit <http://www.icopen.net>



ORBEC 3-D Sensor Application Design Competition

In order to provide an innovative development platform for students, researchers, technicians and engineers, also to arouse public interests to optical engineering, and to enrich the content and form of icOPEN 2018, the "ORBEC 3-D Sensor Application Design Competition" will be held for icOPEN 2018. We sincerely welcome all scholars to the relevant fields to participate this great event. The details of the contest are as follows:

I. Purpose

1. To promote the innovation and development of optical engineering and sensor technology.
2. To advocate innovative thinking, to encourage original, pioneering spirit, and to promote innovative talent training.
3. To promote scientific and technological cooperation and innovation, and to promote the transformation from research to product and reach the integration between industry and research.

II. Requirements

1. The work must be original, novel, matching to the topic. The specific requirements as described in section III.
2. Worldwide undergraduate students, graduate students, researchers, technicians and engineers are all welcomed to participate.
3. For better brain storming, it is recommended to form a 3-5 people team to join the competition.

III. Requirements of the Work

1. The work should match the topic of "3D sensor innovative development and application" Suggested designs are : Robotic vision, SLAM (simultaneous positioning and mapping), Virtual reality, Augmented reality, Body sense games, 3D scanning and measuring, Face recognition, Action capture, and etc.
2. The work requires using the Astra type 3D sensors provided by Shenzhen ORBBEC Technology Co., Ltd. for the design of the competition.
3. The work needs to be oral presented with PPT slides and demonstrated on site. The presentation should contain the basic idea, the plan, the development or the application result, the application foreground and etc. of the design.
4. If the presenter has special needs for the site, he/she has to inform the organizer in advance to set up for the special requirement.
5. The Astra type 3D sensors can be purchased from ORBBEC Technology Co., Ltd. with discount rate (1000 RMB/set) or can be rent from the company for free. Deposit (499 RMB/set) has to be paid for renting. The deposit will be refund after returning the equipment back to the company.

- The copyright of the work belongs to the team.
- The results of the competition will be announced for the first time during icOPEN 2018. The winning team representatives will deliver their acceptance speech at the ceremony.

IV. Entry Process

Phase I (before 2017.12.10): Turn in application forms, contact the staff and inform the number of 3D sensors planned for purchase or rent.

Phase II (before 2018.3.15): Feedback progress form, including name of the design, brief introduction of the design, any special need for the presentation and etc..

Phase III (before 2018.4.20): Send the report of the design to the organizing committee. The members of the technical committee will review the submission and give feedbacks.

Phase IV (on 2018.5.8): On-site demonstration and oral presentation of the design. The award-winning design will be announced during the dinner banquet of icOPEN 2018.

V. Awards

- Winning certification
- Scholarship

	Number of Winner	Scholarship
Grand Prize	1	5000RMB / each
First Prize	2	3000RMB / each
Second Prize	4	2000RMB / each
Third Prize	6	1000RMB / each
Creativity Award	10	500RMB / each

VI. Application Method

Please download the application form (click to download), fill the form out and send it to the following contact person.

VII. Contact

For application submission or related question, please contact:

Mr. Shijie Feng

Email: shijiefeng@njust.edu.cn

For more information about icOPEN 2018 and the ORBBEC 3-D Sensor Application Design Competition, please visit: <http://www.icopen.net>